

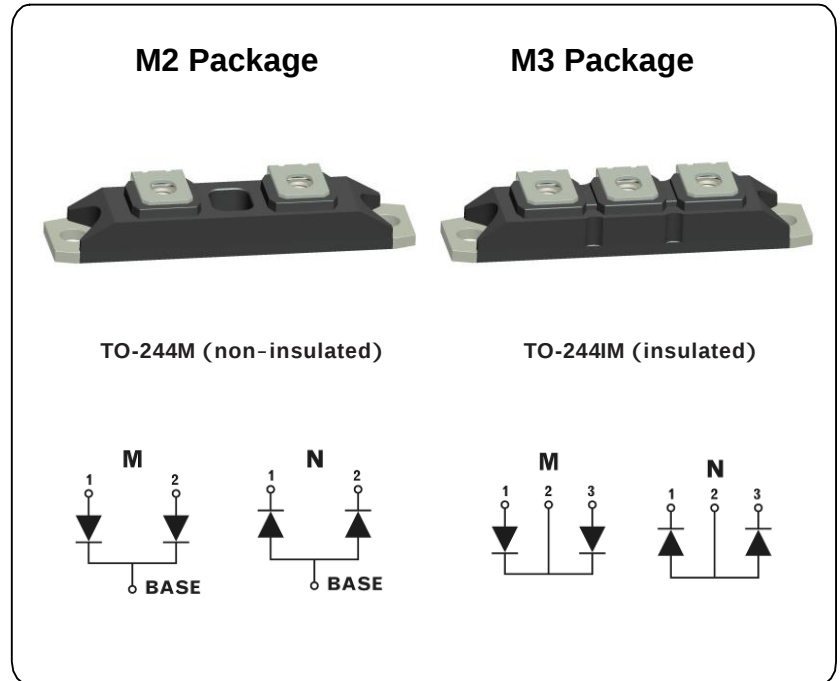
Super Fast Recovery Diode ,400A

Features

- International standard package with DCB ceramic base plate
- Dual Diode construction
- Low Leakage Current
- Low forward voltage drop
- High surge current capability
- Super Fast Switching

Typical Applications

- Antiparallel diode for high frequency switching devices
- Free wheeling diode in converters and motor control circuits
- Inductive heating and melting
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders



Maximum Ratings

Parameter	Symbol	Test Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		600	V
RMS reverse voltage	V_{RMS}		420	V
DC blocking voltage	V_{DC}		600	V
Average forward current	$I_{F(AV)}$	$TC \leq 120^{\circ}C$	400	A
Non-repetitive forward surge current, half sine-wave	I_{FSM}	$TC = 25^{\circ}C$	2700	A

Electrical Specifications

Parameter	Symbol	Test Conditions	Values	Unit
DC forward voltage	V_F	$I_F = 100A$ $T_J = 25^{\circ}C$	1.2	V
Maximum DC reverse current	I_R	$V_R = \text{Rated } V_{RRM}$ $T_J = 25^{\circ}C$	20	μA
		$V_R = \text{Rated } V_{RRM}$ $T_J = 125^{\circ}C$	3	mA
Maximum Reverse Recovery Time	t_{rr}	$I_F = 0.5A$, $I_R = 1A$, $I_{RR} = 0.25A$	180	ns
Reverse recovery charge (Area Under the curve Defined by I_{RRM} And t_{rr})	Q_{rr}	$V_{DD} = 300V$, $I_F = 200A$, $dif/dt = 200A/\mu s$; $T_J = 25^{\circ}C$	-	nc
Diode Peak Reverse Recovery Current	I_{RRM}		16	A
$S = t_b/t_a$	S		0.6	

Thermal - Mechanical Specifications

Parameter	Symbol	Test Conditions	Values	Unit
Thermal resistance junction to case(M2/M3)	R_{thjc}	Per diode	0.14/0.35	$^{\circ}\text{C/W}$
Junction and storage temperature range	T_J, T_{stg}		-40 to 150	$^{\circ}\text{C}$
Mounting Torque	Mt	To terminals(M6)	$4 \pm 15\%$	Nm
	Ms	To heatsink(M6)	$5 \pm 15\%$	
Module(Approximately)	Weight		85	g
Maximum RMS insulation voltage (for insulated type)	M3 (Insulated)	Visol	Ac.50Hz; R.M.S; 1min	V
			Ac.50Hz; R.M.S; 1sec	

Performance Curves

Fig.1 Forward Current vs Forward Voltage

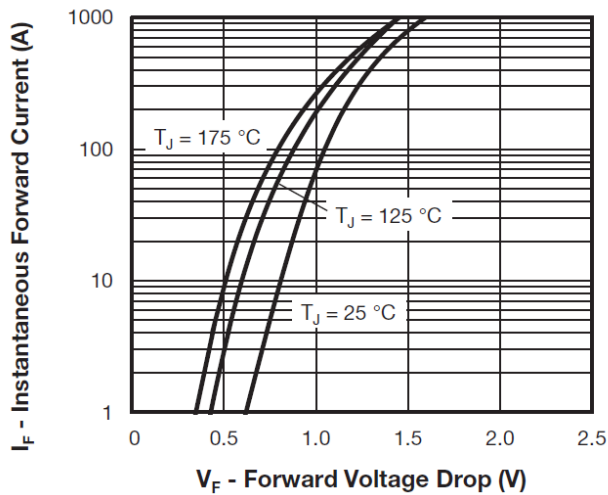


Fig.2 Reverse Current vs Reverse Voltage

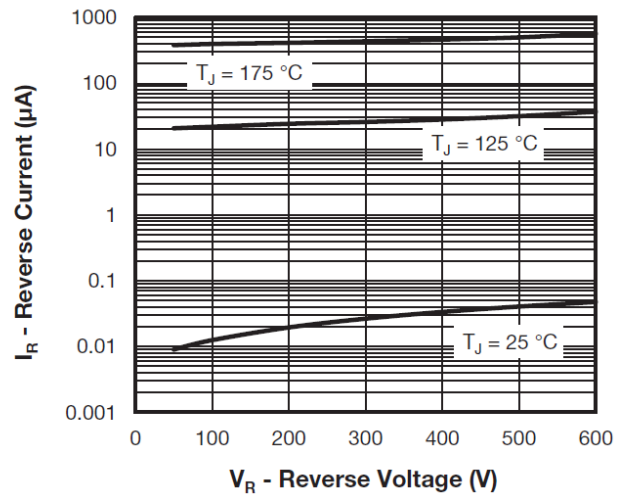


Fig.3 Reverse Recovery Parameter Test Circuit

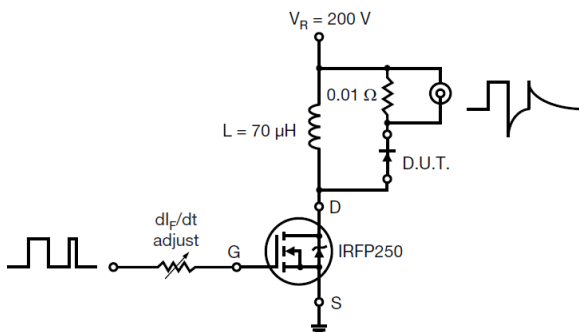
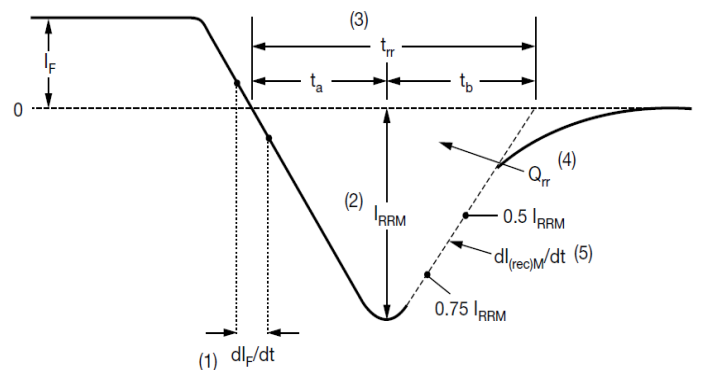


Fig.4 Reverse Recovery Waveform and Definitions


 (1) dl_F/dt - rate of change of current through zero crossing

 (2) I_{RRM} - peak reverse recovery current

 (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.

 (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

 (5) $dl_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Ordering Information Tabel

Device code

C M DU 400 I M - 06

CE's power module

"M" = common Cathode configuration

"N" = common Anode configuration

DS for Schottky Barrier Diode

Maximum average forward current, A

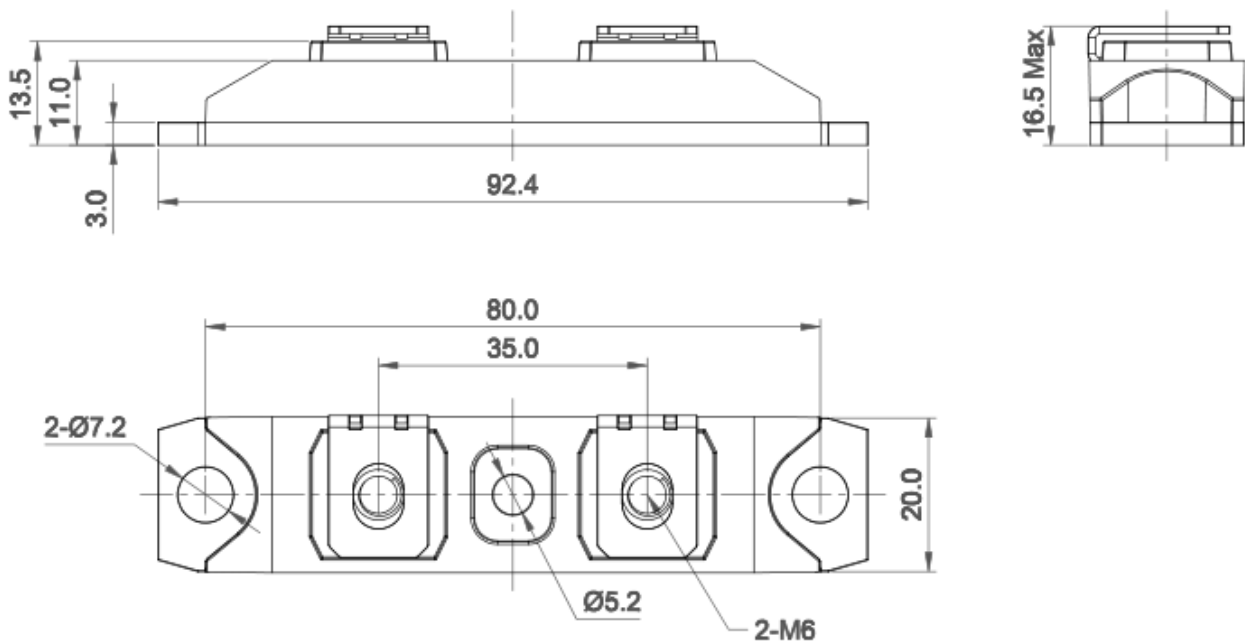
I = Insulated Package

M = Molding

Voltage rating (06 = 600V)

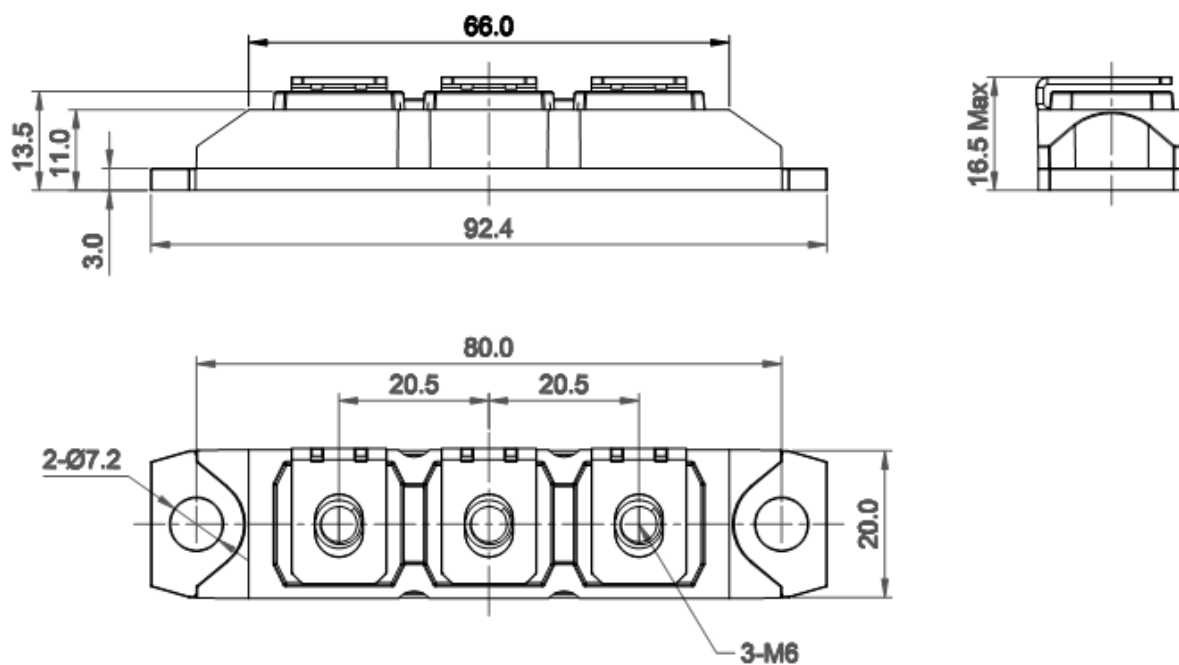
Package Outline Information

M2 Package



Dimensions in mm

M3 Package



Dimensions in mm